

CHIP INDUCTOR

CIW & CIWF TYPE

INTRODUCTION

This wire wound type chip inductor is widely used in communication applications such as cell phones, pagers, television tuners, radios and other electronic devices. The wire wound features are advance in higher self-resonate frequency, better Q factor and much stable performance.

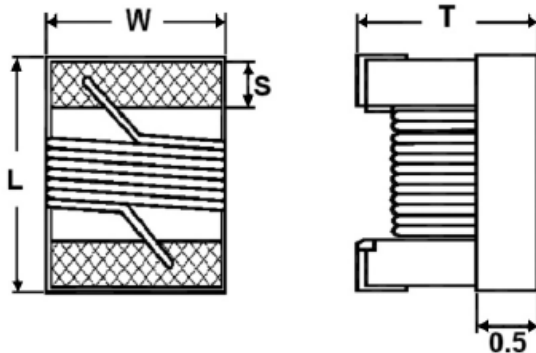
FEATURES

- Operating temperature -40°C to $+85^{\circ}\text{C}$.
- Excellent solderability and resistance to soldering heat.
- Suitable for flow and reflow soldering.
- Good dimensions, high reliability and easy surface mounting for assemble.
- Wide range of inductance value for flexible needs.

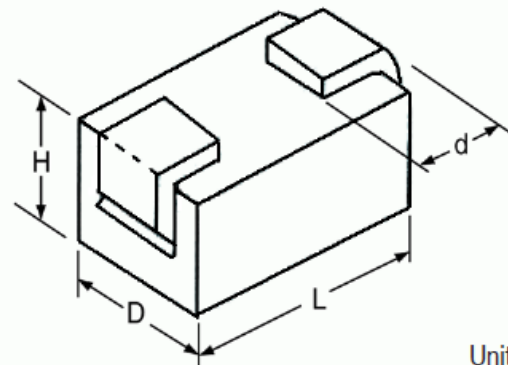
DIMENSIONS

Unit : mm

CIW

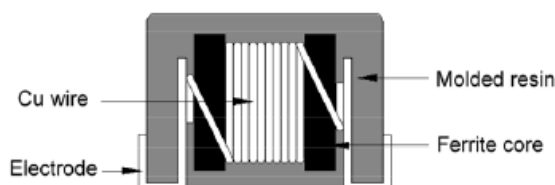


TYPE	L MAX.	W MAX.	T MAX.	S
CIW1005 (0402)	1.70	0.76	0.61	0.20 ± 0.1
CIW1608 (0603)	1.80	1.15	1.10	0.35 ± 0.1
CIW2012 (0805)	2.29	1.75	1.55	0.40 ± 0.1
CIW2520 (1008)	2.92	2.79	2.05	0.50 ± 0.1
CIW3216 (1206)	3.45	1.90	1.40	0.50 ± 0.1
CIW3225 (1210)	3.45	2.80	2.50	0.50 ± 0.1



Unit : mm

CIWF



TYPE	L	D	H	d
CIWF2520	2.5 ± 0.3	2.0 ± 0.2	1.8 ± 0.2	0.4 ± 0.1
CIWF3225	3.2 ± 0.2	2.5 ± 0.2	2.2 ± 0.2	0.4 ± 0.1

TEST	TEST METHOD	LIMITS
VIBRATION TEST	Test device shall be soldered on the substrate Oscillation Frequency : 10 to 55 to 10Hz for 1min Amplitude : 1.5mm Time : 2hours for each axis (X, Y & Z), total 6hours	Appearance : No damage L changes : within $\pm 5\%$ Q changes : within $\pm 10\%$
RESISTANCE TO SOLDERING HEAT	Soldering Temperature : $270 \pm 5^{\circ}\text{C}$ Immersion Time : $10 \pm 2\text{sec}$	
COMPONENT ADHESION (PUSH TEST)	The device should be soldered ($260 \pm 5^{\circ}\text{C}$ for 10 seconds) to tinned copper subs rate. A dynamiter force gauge should be applied to the side of the components. The device must stand with a minimum force of 2 or 4 pounds without a failure of adhesion on termination	1 lbs. for 0402 2 lbs. for 0603 3 lbs. for the rest
DROP TEST	Dropping the chip by each side and each corner and drop for 10 times in total. Drop height : 100cm; Drop weight : 125g	No damage
SOLDERABILITY TEST	Inductor shall be dipped in a melted solder bath at $245 \pm 5^{\circ}\text{C}$ for 5 seconds.	90% covered with soldering
RESISTANCE TO SOLVENT TEST	MIL-STD202F, Method 215D	No damage on appearance and marking.